

MATERIAL DECLARATION SHEET



Material Number	CDWBS16 Series			
Product Line	Diode Products			
Compliance Date	1 Jan 2006			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Frame	Copper Alloy	0.075700	Copper	7440-50-8	95.2	48.430	50.870
				Tin	7440-31-5	4.8	2.4470	
2	Chip	Silicon	0.014340	Silicon	7440-21-3	97.99	9.440	9.6370
				Other material		1.99	0.1927	
3	Bond Wire	Gold	0.000352	Gold	7440-57-5	99.02	0.2342	0.2365
				Silicon	7440-21-3	0.976	0.0023	
4	Die Attach	High Temp Solder	0.000808	Silver	7440-22-4	1.98	0.0108	0.5430
				Lead	7439-92-1	88.011	0.4779	
				Tin	7440-31-5	10	0.0543	
5	Molding Component	Epoxy Material	0.057600	Silica fused	60676-86-0	84.99	32.9	38.710
				Epoxy resin	68928-70-1	10	3.8710	
				Phenol resin	29690-82-2	5.99	2.3220	
		Total weight	0.148800					

This Document was updated on: 18-march 2009

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.